

### **Amendments to the Specification**

Please replace the paragraph number 46 with the following revised paragraph:

[46] Figure 7B shows a ~~top~~ view of ~~a portion~~ portions of a surface of a proximity head in accordance with one embodiment of the present invention.

Please replace the paragraph number 103 with the following revised paragraph:

[103] Figure 7B shows a ~~top~~ view of ~~a portion~~ portions of a surface of a proximity head 106 in accordance with one embodiment of the present invention. In the ~~top~~ view of one embodiment, from left to right are a set of the source inlet 302, a set of the source outlet 304, a set of the source inlet 306, a set of the source outlet 304, and a set of the source inlet 302 in respective portions or regions of the surface of the proximity head 106. Therefore, as N<sub>2</sub>/IPA and DIW are inputted into the region between the surface of the proximity head 106 and the wafer 108, the vacuum removes the N<sub>2</sub>/IPA and the DIW along with any fluid film that may reside on the wafer 108. The source inlets 302, the source inlets 306, and the source outlets 304 described herein may also be any suitable type of geometry such as for example, circular opening, square opening, etc. In one embodiment, the source inlets 302 and 306 and the source outlets 304 have circular openings.